

VIA Launches VIA SOM-9X20 Featuring Qualcomm® Snapdragon™ 820 Embedded Platform

Highly-integrated ultra-compact system-on-module accelerates development of next-generation Enterprise IoT and embedded devices

NEW TAIPEI CITY, TAIPEI, TAIWAN, October 26, 2017 /EINPresswire.com/ -- Taipei, Taiwan, 26 October, 2017 - [VIA Technologies, Inc.](#), today announced the launch of the VIA [SOM-9X20](#) system-on-module (SoM) powered by the Qualcomm® Snapdragon™ 820 embedded platform, a product of Qualcomm Technologies, Inc., a subsidiary of Qualcomm Incorporated.



The VIA SOM-9X20 is an ultra-compact SoM that harnesses the leading-edge performance and low power consumption of the Snapdragon 820 embedded platform to provide a highly-flexible solution for enabling the rapid development of a variety of Enterprise IoT and embedded system applications ranging from human-machine interface (HMI), surveillance, and digital signage to robotics, cameras, and video conferencing.

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The VIA SOM-9X20 is designed to enable our customers to accelerate the development of groundbreaking new products with stunning 4K video capabilities for rapidly-emerging applications”

Richard Brown, VP of International Marketing, VIA

“Combining cutting-edge computing, graphics, and video capabilities with advanced wireless connectivity and low power consumption, the Snapdragon 820 meets the exacting performance and power efficiency requirements of next-generation Enterprise IoT and embedded devices,” said Richard Brown, Vice-President of International Marketing, VIA Technologies, Inc. “The VIA SOM-9X20 is designed to enable

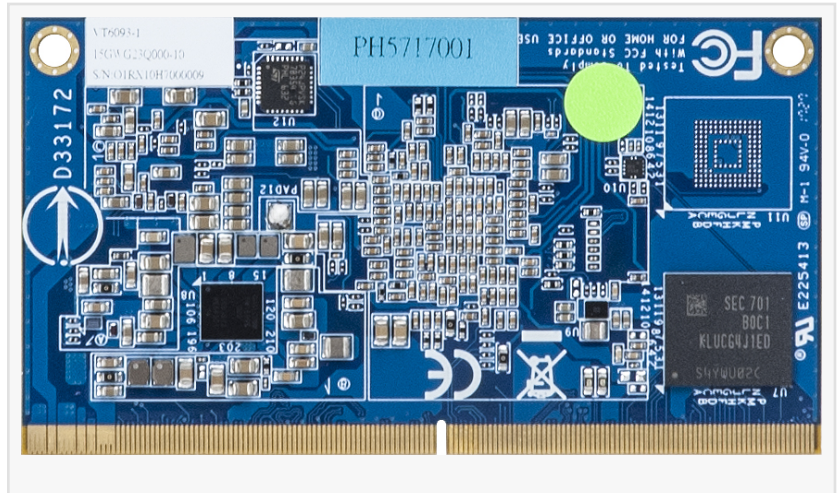
our customers to accelerate the development of groundbreaking new products with stunning 4K video capabilities for rapidly-emerging applications such as machine intelligence, computer vision, and Augmented and Virtual Reality.”

“The Snapdragon 820 embedded platform provides the performance, energy efficiency, and connectivity required in cutting-edge Enterprise IoT devices,” said Jeffery Torrance, vice president, business development, Qualcomm Technologies, Inc. “We are delighted that VIA is making the power of Snapdragon available in an ultra-compact SoM that will help developers quickly create new and exciting commercial IoT systems, scenarios, and use cases.”

Snapdragon 820 processor

The Snapdragon 820 processor includes the following features:

- Qualcomm® Kryo™ CPU: Designed to deliver maximum performance and low power consumption, Kryo is Qualcomm Technologies' first custom 64-bit quad-core CPU, manufactured in advanced 14nm FinFET LPP process
- Qualcomm® Adreno™ 530 GPU: Up to 40% better graphics and compute performance for improved visual fidelity while reducing power consumption than previous generations
- Qualcomm Spectra™ 14-bit dual image signal processors (ISPs) engineered to deliver high resolution DSLR-quality images using heterogeneous compute for advanced processing and additional power savings, supports up to 28MP sensors with zero shutter lag
- Qualcomm® Hexagon™ 680 DSP includes Hexagon Vector eXtensions (HVX) and Sensor Core with Low Power Island for constant sensor processing



VIA SOM-9X20

The VIA SOM-9X20 is a highly-integrated system-on-module powered by the Qualcomm Snapdragon 820 embedded platform. Measuring a mere 8.2cm x 4.5cm, the module features 64GB eMMC Flash memory and 4GB LPDDR4 SDRAM onboard and offers rich I/O and display expansion options through its MXM 3.0 314-pin connector, including USB 3.0, USB 2.0, HDMI 2.0, SDIO, PCIe, MIPI CSI, MIPI DSI, and multi-function pins for UART, I2C, SPI, and GPIO.

The VIA SOM-9X20 module also provides a full set of advanced wireless connectivity features including GPS, BT 4.1, and Wi-Fi 802.11 a/b/g/n/ac through an integrated combo module featuring two antenna connectors. A multi-I/O evaluation carrier board is available to accelerate system development. Customers can also utilize VIA's extensive technical support and design assistance services to develop a custom baseboard.

The VIA SOM-9X20 comes with a BSP that features Android 7.1.1 as well as the VIA Smart ETK (Embedded Tool Kit) comprising a number of APIs, including Watchdog Timer (WDT) for safeguarding against system crashes, GPIO access, RTC for auto-power on, and a sample app.

A full set of hardware and software customization services that speed up time to commercialization and minimize development costs is available. A full turnkey development service can also be provided for interested customers.

For more information about the VIA SOM-9X20 please visit:

<https://www.viatech.com/en/boards/modules/som-9x20/>

For images related to this release, please visit: <https://www.viagallery.com/som-9x20/>

About VIA Technologies, Inc.

VIA Technologies, Inc is a global leader in the development of highly-integrated embedded platform and system solutions for M2M, IoT, and Smart City applications, ranging from video walls and digital signage to healthcare and industrial automation. Headquartered in Taipei, Taiwan, VIA's global network links the high tech centers of the US, Europe and Asia, and its customer base includes the

many world's leading hi-tech, telecommunications, consumer electronics industry brand names.
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Note to reporters, editors and writers: VIA is written in ALL CAPS.

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